

L Number	Hits	Search Text	DB	Time stamp
1	5	assembly and pads near copp r and bump near aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:02
2	5	("4130454" "5244539" "5268048" "5574386" "6134776").PN.	USPAT	2003/10/21 16:01
3	0	pcb near assembly and pads near copper and bump near aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:02
4	0	pcb and pads near copper and bump near aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:02
5	6	pads near copper and bump near aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:05
6	5	assembly and copper near pads and aluminum near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:07
7	3	mounting adj pads near copper and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:08
8	0	mounting adj pads near copper and bumps near aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:09
9	0	mounting adj pads near copper and bumps same aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:09
10	0	mounting adj pads near copper and bumps and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:09

11	4	mounting adj pads near copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:12
12	0	mounting adj pads near copper and aluminum near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:12
13	6	mounting adj pads and aluminum near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:13
14	4	copper adj pads and aluminum near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:13
15	1	"6139977".PN.	USPAT	2003/10/21 16:15
16	18	("4000842" "4005472" "4380042" "4849856" "4873123" "4899207" "4914551" "4979663" "5029386" "5034591" "5098008" "5099393" "5278724" "5336564" "5386341" "5397921" "5435732" "5770480").PN.	USPAT	2003/10/21 16:16
-	2	6381837.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 15:58
-	11	("3801388" "3953924" "4404059" "5177863" "5453581" "5489750" "5542174" "5738797" "5932993" "6115262" "6169253").PN.	USPAT	2003/10/21 10:27
-	0	"an electronic circuit assembly".ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 10:39
-	0	"an electronic circuit assembly"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 10:40
-	645	"electronic circuit assembly"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 10:40

-	42	"electronic circuit assembly" and 29/\$.ccls.	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2003/10/21 10:49
-	8	("5132864" "5357060" "5386087" "5425647" "5453581" "5486657" "5644475" "5707714").PN.	USPAT	2003/10/21 10:44
-	11	("3801388" "3953924" "4404059" "5177863" "5453581" "5489750" "5542174" "5738797" "5932993" "6115262" "6169253").PN.	USPAT	2003/10/21 10:47
-	270	29/840.ccls. and substrate and pads and chip and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:13
-	4	("3373481" "5874780" "5889326" "6081997").PN.	USPAT	2003/10/21 10:54
-	43	("4157932" "4554033" "4612083" "4640981" "4680226" "4749120" "4818728" "4868979" "4917466" "4967314" "5074947" "5084961" "5086558" "5136365" "5147210" "5196371" "5237130" "5296063" "5298279" "5318651" "5329423" "5341564" "5363277" "5384952" "5477419" "5543585" "5545281" "5611140" "5637176" "5667884" "5674780" "5686702" "5714252" "5747101" "5840417" "5843251" "5861678" "5863970" "5879761" "5918364" "5925930" "5975408" "6027575").PN.	USPAT	2003/10/21 10:58
-	167	29/832.ccls. and substrate and pads and chip and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:36
-	12	("3670409" "4818728" "4893172" "4975079" "5006792" "5086337" "5196726" "5199879" "5615824" "5802699" "5880590" "5984691").PN.	USPAT	2003/10/21 11:17

-	40	("2014524" "2774747" "3401126" "3429040" "3757075" "3971610" "4113981" "4157932" "4442966" "4554033" "4587038" "4612083" "4640981" "4648179" "4695404" "4719140" "4764804" "4818728" "4840302" "4872261" "4914057" "4917466" "4922321" "4967314" "4985107" "4991000" "5001302" "5068714" "5074947" "5086558" "5090119" "5147210" "5187020" "5196371" "5218234" "5270253" "5290423" "5329423" "5508228" "5674780").PN.	USPAT	2003/10/21 11:22
-	0	29/832.ccls. and insulation near substrate and mounting adj pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:36
-	1	29/832.ccls. and insulation near substrate and mounting adj pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:37
-	3	29/832.ccls. and insulation same substrate and mounting adj pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:37
-	80	29/\$.ccls. and insulation same substrate and pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:58
-	6	insulation near substrate and mounting near pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:00
-	2	("5844304" "6022757").PN.	USPAT	2003/10/21 11:59
-	16	insulation near substrate and mounting near pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:01
-	229	ceramic near substrate and mounting near pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:01

-	1	eramic near substrate and mounting near pads and component near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:04
-	3	("4912545" "4922322" "5196726").PN.	USPAT	2003/10/21 12:04
-	6	substrate and mounting near pads and component near bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:05
-	57	Jairazbhoy near Vivek .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:05
-	12	29/832.ccls. and insulation same substrate and pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 12:38
-	278	pcb and footprint and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:09
-	278	pcb and footprint and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:10
-	262	pcb and footprint and pads and bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 14:51
-	18	("4423468" "5047711" "5059557" "5126286" "5222014" "5235496" "5239191" "5239198" "5304843" "5356838" "5388029" "5731222" "5731630" "5783464" "5832600" "5880011" "5888884" "5904496").PN.	USPAT	2003/10/21 13:19
-	1	1999-337361.NRAN.	DERWENT	2003/10/21 14:46
-	4	561547.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 14:52

-	2	5615477.pn.	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB USPAT	2003/10/21 14:52
-	48	("3868724" "3965568" "4219882" "4221047" "4425401" "4628406" "4647959" "4700473" "4730238" "4748495" "4772936" "4774634" "4814855" "4862153" "4878098" "4891789" "4893216" "4906823" "4924352" "4942452" "4953460" "4967950" "4980034" "5001542" "5008997" "5019673" "5019944" "5021630" "5033665" "5045975" "5073118" "5109601" "5111279" "5112462" "5132879" "5133495" "5137791" "5168346" "5203075" "5227589" "5242100" "5261593" "5275330" "5289631" "5316787" "5364707" "5435732" "5450290").PN.		2003/10/21 14:53